

RELIABILITY REPORT
FOR
MAX6747KA29+
PLASTIC ENCAPSULATED DEVICES

May 14, 2009

MAXIM INTEGRATED PRODUCTS

120 SAN GABRIEL DR.
SUNNYVALE, CA 94086

Approved by
Ken Wendel
Quality Assurance
Director, Reliability Engineering

Conclusion

The MAX6747KA29+ successfully meets the quality and reliability standards required of all Maxim products. In addition, Maxim's continuous reliability monitoring program ensures that all outgoing product will continue to meet Maxim's quality and reliability standards.

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I. Device Description

A. General

The MAX6746-MAX6753 low-power microprocessor (μ P) supervisory circuits monitor single/dual system supply voltages from 1.575V to 5V and provide maximum adjustability for reset and watchdog functions. These devices assert a reset signal whenever the VCC supply voltage or RESET IN falls below its reset threshold or when manual reset is pulled low. The reset output remains asserted for the reset timeout period after VCC and RESET IN rise above the reset threshold. The reset function features immunity to power-supply transients. The MAX6746-MAX6753 have $\pm 2\%$ factory-trimmed reset threshold voltages in approximately 100mV increments from 1.575V to 5.0V and/or adjustable reset threshold voltages using external resistors. The reset and watchdog delays are adjustable with external capacitors. The MAX6746-MAX6751 contain a watchdog select input that extends the watchdog timeout period by 128x. The MAX6752/MAX6753 contain a window watchdog timer that looks for activity outside an expected window of operation. The MAX6746-MAX6753 are available with a push-pull or open-drain active-low RESET output. The MAX6746-MAX6753 are available in an 8-pin SOT23 package and are fully specified over the automotive temperature range (-40°C to $+125^{\circ}\text{C}$).

II. Manufacturing Information

A. Description/Function:	μP Reset Circuits with Capacitor-Adjustable Reset/Watchdog Timeout Delay
B. Process:	B8
C. Number of Device Transistors:	
D. Fabrication Location:	Oregon
E. Assembly Location:	Hana Thailand, Carsem Malaysia
F. Date of Initial Production:	July 27, 2002

III. Packaging Information

A. Package Type:	8-pin SOT23
B. Lead Frame:	Copper
C. Lead Finish:	100% matte Tin
D. Die Attach:	Conductive Epoxy
E. Bondwire:	Gold (1 mil dia.)
F. Mold Material:	Epoxy with silica filler
G. Assembly Diagram:	#05-9000-0417
H. Flammability Rating:	Class UL94-V0
I. Classification of Moisture Sensitivity per JEDEC standard J-STD-020-C	Level 1
J. Single Layer Theta Jb:	110°C/W
K. Single Layer Theta Jc:	80°C/W

IV. Die Information

A. Dimensions:	24 X 80 mils
B. Passivation:	Si ₃ N ₄ /SiO ₂ (Silicon nitride/ Silicon dioxide)
C. Interconnect:	Aluminum/Si (Si = 1%)
D. Backside Metallization:	None
E. Minimum Metal Width:	0.8 microns (as drawn)
F. Minimum Metal Spacing:	0.8 microns (as drawn)
G. Bondpad Dimensions:	5 mil. Sq.
H. Isolation Dielectric:	SiO ₂
I. Die Separation Method:	Wafer Saw

V. Quality Assurance Information

A. Quality Assurance Contacts:	Ken Wendel (Director, Reliability Engineering) Bryan Preeshl (Managing Director of QA)
B. Outgoing Inspection Level:	0.1% for all electrical parameters guaranteed by the Datasheet. 0.1% For all Visual Defects.
C. Observed Outgoing Defect Rate:	< 50 ppm
D. Sampling Plan:	Mil-Std-105D

VI. Reliability Evaluation

A. Accelerated Life Test

The results of the 135°C biased (static) life test are shown in Table 1. Using these results, the Failure Rate (λ) is calculated as follows:

$$\lambda = \frac{1}{\text{MTTF}} = \frac{1.83}{192 \times 4340 \times 45 \times 2} \quad (\text{Chi square value for MTTF upper limit})$$

(where 4340 = Temperature Acceleration factor assuming an activation energy of 0.8eV)

$$\lambda = 23.9 \times 10^{-9}$$

$$\lambda = 23.9 \text{ F.I.T. (60\% confidence level @ 25°C)}$$

The following failure rate represents data collected from Maxim's reliability monitor program. Maxim performs quarterly 1000 hour life test monitors on its processes. This data is published in the Product Reliability Report found at <http://www.maxim-ic.com/>. Current monitor data for the B8 Process results in a FIT Rate of 1.29 @ 25C and 15.6 @ 55C (0.8 eV, 60% UCL)

B. Moisture Resistance Tests

The industry standard 85°C/85%RH or HAST testing is monitored per device process once a quarter.

C. E.S.D. and Latch-Up Testing

The MS62-1 die type has been found to have all pins able to withstand an ESD transient pulse of:

HBM: +/-2500 V per JEDEC JESD22-A114
CDM: +/-750 V per JEDEC JESD22-C101

Latch-Up testing has shown that this device withstands a current of +/-200 mA.

Table 1
Reliability Evaluation Test Results

MAX6747KA29+

TEST ITEM	TEST CONDITION	FAILURE IDENTIFICATION	SAMPLE SIZE	NUMBER OF FAILURES
Static Life Test (Note 1)	Ta = 135°C Biased Time = 192 hrs.	DC Parameters & functionality	45	0
Moisture Testing (Note 2) 85/85	Ta = 85°C RH = 85% Biased Time = 1000hrs.	DC Parameters & functionality	77	0
Mechanical Stress (Note 2) Temperature Cycle	-65°C/150°C 1000 Cycles Method 1010	DC Parameters & functionality	77	0

Note 1: Life Test Data may represent plastic DIP qualification lots.

Note 2: Generic Package/Process data